$D_2$ 

# **Dual N-Channel 30-V (D-S) MOSFET**

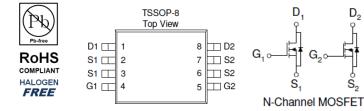
### **Key Features:**

- Low r<sub>DS(on)</sub> trench technology
- · Low thermal impedance
- · Fast switching speed

### **Typical Applications:**

- Power Routing
- Li Ion Battery Packs
- Level Shifting and Driver Circuits

PRODUCT SUMMARY			
Vds (V)	$r_{DS(on)}(m\Omega)$	I⊳(A)	
30	28 @ V <sub>GS</sub> = 4.5V	5.3	
30	40 @ V <sub>GS</sub> = 2.5V	4.4	



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)					
Parameter		Symbol	Limit	Units	
Drain-Source Voltage		V <sub>DS</sub>	30	V	
te-Source Voltage		V <sub>GS</sub>	±12	V	
	T <sub>A</sub> =25°C		5.3		
Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =70°C		4.1	А	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	20		
Continuous Source Current (Diode Conduction) <sup>a</sup>	ا <sub>S</sub>	1.8	А		
Dever Director a	T <sub>A</sub> =25°C	P <sub>D</sub>	1.15	W	
Power Dissipation <sup>a</sup>	T <sub>A</sub> =70°C		0.7	vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	-55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Ambient <sup>a</sup>	t <= 10 sec	$R_{\thetaJA}$	110	°C/W	
	Steady State	٩٢٩	150	C/VV	

Notes

- Surface Mounted on 1" x 1" FR4 Board. a.
- b. Pulse width limited by maximum junction temperature

## **Electrical Characteristics**

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
		Static				
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \text{ uA}$	0.4			V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 12 V$			±100	nA
Zero Gate Voltage Drain Current	1	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$			1	uA
	IDSS	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			10	uЛ
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	8			А
Drain Sauras On Desistance a	r	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 2 \text{ A}$			28	mΩ
Drain-Source On-Resistance <sup>a</sup>	r <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 1.6 \text{ A}$			40	11122
Forward Transconductance <sup>a</sup>	<b>g</b> <sub>fs</sub>	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 2 \text{ A}$		15		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_{S} = 0.9 \text{ A}, V_{GS} = 0 \text{ V}$		0.64		V
		Dynamic <sup>b</sup>				
Total Gate Charge	Qg	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 4.5 V,		8.7		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 13 V, V_{GS} = 4.3 V,$ $I_{D} = 2 A$		1.5		nC
Gate-Drain Charge	$Q_gd$	10 - 2  A		2.7		
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DS} = 15 \text{ V}, \text{ R}_1 = 7.5 \Omega,$		10		
Rise Time	t <sub>r</sub>	$V_{\rm DS} = 15$ V, $N_{\rm L} = 7.5$ Ω, $I_{\rm D} = 2$ A,		17		200
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{\text{GEN}} = 4.5 \text{ V}, \text{ R}_{\text{GEN}} = 6 \Omega$		40		ns
Fall Time	t <sub>f</sub>	$V_{\text{GEN}} = 4.5 \text{ V}, \text{ (C}_{\text{EN}} = 0.22 $		11		
Input Capacitance	C <sub>iss</sub>			641		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ Mhz}$		52		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			46		

#### Notes

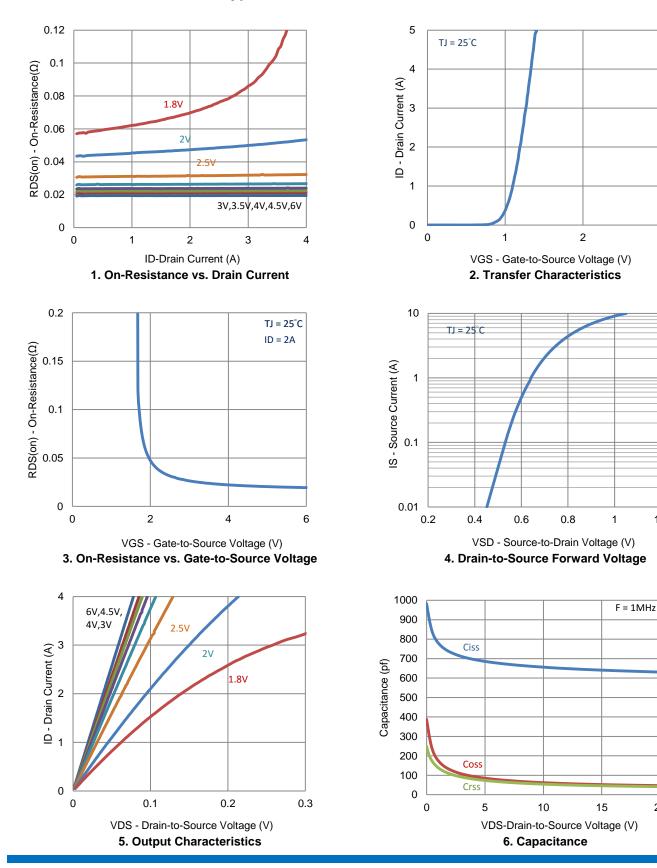
- a. Pulse test: PW <= 300us duty cycle <= 2%.
- b. Guaranteed by design, not subject to production testing.

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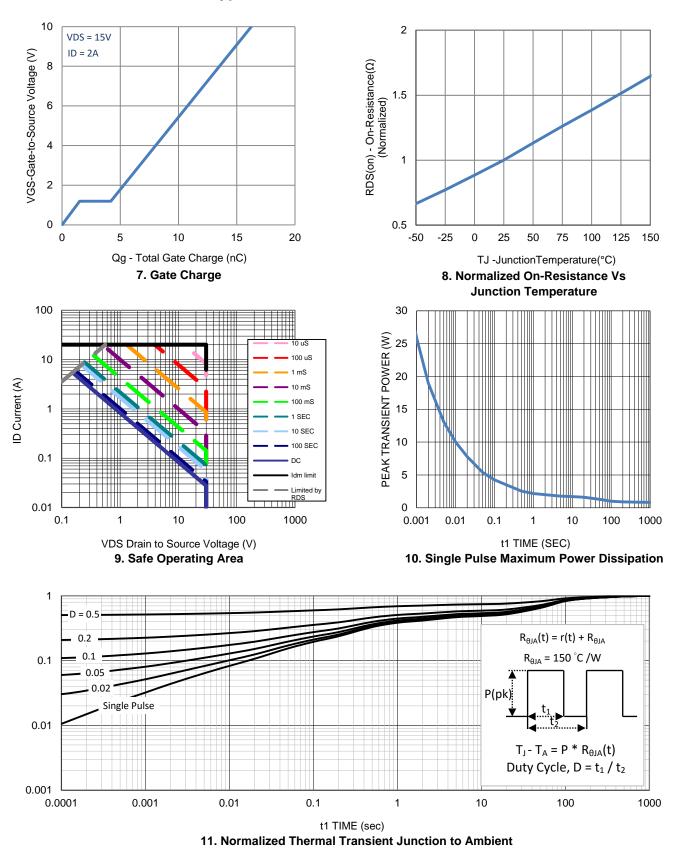
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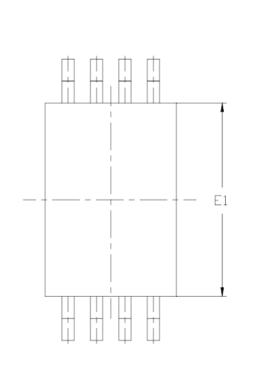
### **Typical Electrical Characteristics**



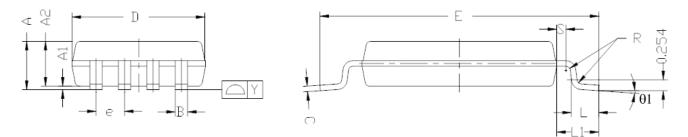
# **Typical Electrical Characteristics**

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### **Package Information**



	MILLIMET			
DIM.	MIN.			
A	1.05	1.10	1.20	
A(1)	0.05	0.10	0.15	
A(2)	0.99	1.02	1.05	
В	0.19	0.25	0.30	
С		0.127		
D	2.90	3.00	3.10	
E	6.20	6.40	6.60	
E1	4.30	4.40	4.50	
e	0.65BSC			
L	0,45	0.60	0.75	
L1	0,90	1.00	1.10	
Y			0.10	
θ1	0°	4°	8°	
R	0.09			
S	0.20			



#### Note:

- 1. All Dimension Are In mm.
- 2. Package Body Sizes Exclude Mold Flash, Protrusion Or Gate Burrs. Mold Flash, Protrusion Or Gate Burrs Shall Not Exceed 0.10 mm Per Side.
- 3. Package Body Sizes Determined At The Outermost Extremes Of The Plastic Body Exclusive Of Mold Flash, Tie Bar Burrs, Gate Burrs And Interlead Flash, But Including Any Mismatch Between The Top And Bottom Of The Plastic Body.
- 4. The Package Top May Be Smaller Than The Package Bottom.
- Dimension "B" Does Not Include Dambar Protrusion. Allowable Dambar Protrusion Shall Be 0.08 mm Total In Excess Of "B" Dimension At Maximum Material Condition. The Dambar Cannot Be Located On The Lower Radius Of The Foot.